

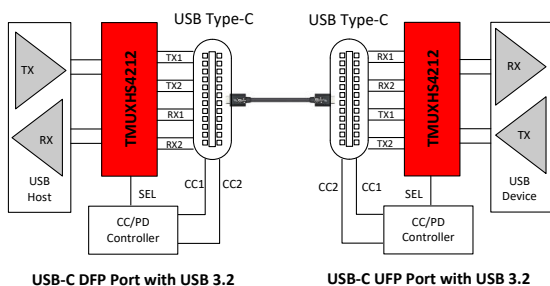
# TMUXHS4212 2 チャンネル差動 2:1 マルチプレクサ / 1:2 デマルチプレクサ

## 1 特長

- 双方向の 2:1 マルチプレクサ / 1:2 デマルチプレクサ
- 最高 10Gbps の USB 3.2 (Gen 2.0)、最高 16Gbps の PCI Express (Gen 4.0) をサポート
- SATA、SAS、Mipi® DSI/CSI、FPD-Link III、LVDS、SFI、イーサネット® インターフェイスにも対応
- 13GHz の -3dB 差動帯域幅
- 動的特性
  - 挿入損失: -1.3dB (5GHz)、-1.8dB (8GHz)
  - 反射損失: -13dB (5GHz)、-12dB (8GHz)
  - オフ・アイソレーション: -22dB (5GHz)、-20dB (8GHz)
- 適応型同相電圧トラッキング
- 0~1.8V の同相電圧をサポート
- 単一 V<sub>CC</sub> 電源電圧: 3.3 または 1.8V
- 超低消費電力: 180μA (アクティブ時)、2μA 未満 (スタンバイ時)
- 産業用温度範囲 (-40°C~105°C) のオプション
- 2.5mm × 4.5mm の QFN パッケージで供給

## 2 アプリケーション

- PC とノート PC
- スマートフォン、タブレット、テレビ
- ゲーム、ホームシアター、およびエンターテインメント
- データセンターおよびエンタープライズ・コンピューティング
- 医療用アプリケーション
- 試験および測定機器
- ファクトリ・オートメーション / 制御
- 航空宇宙 / 防衛
- 電子 POS (EPOS)
- ワイヤレス・インフラ



## 3 概要

TMUXHS4212 は、マルチプレクサまたはデマルチプレクサ構成の高速、双方向パッシブ・スイッチです。USB Type-C™ や PCI Express などの多くのアプリケーションに適しています。TMUXHS4212 は、最高 16Gbps のデータ・レートの各種高速差動インターフェイスに使用できる汎用アナログ差動パッシブ・マルチプレクサ / デマルチプレクサです。電気的チャンネルのシグナル・インテグリティに余裕がある場合には、さらに高いデータ・レートで使用できます。TMUXHS4212 は、同相電圧範囲 (CMV) が最大 0~1.8V、差動振幅が最大 1800mVpp の差動信号をサポートしています。適応型 CMV トラッキングにより、デバイスを通るチャンネルが同相電圧範囲全体にわたって変化しないようにしています。

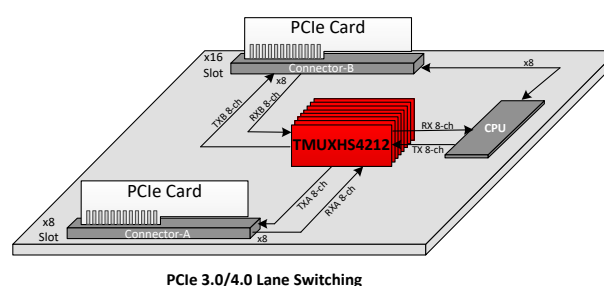
TMUXHS4212 の動的特性は、高速なスイッチング、信号アイ・ダイアグラムの減衰の最小化、超低ジッタを可能にしています。このデバイスのシリコン設計は、高い周波数の信号帯域でも優れた周波数応答が得られるように最適化されています。このデバイスのシリコン信号トレースとスイッチ・ネットワークは、最良のペア内スキュー性能が得られるように整合されています。

TMUXHS4212 は、産業用および高信頼性用途などの各種の堅牢なアプリケーションに適した拡張産業用温度範囲で動作します。

### 製品情報(1)

部品番号	パッケージ	本体サイズ (公称)
TMUXHS4212	VQFN (20)	2.50mm ×
TMUXHS4212I		4.50mm、0.5mm ピッチ

- (1) 利用可能なすべてのパッケージについては、このデータシートの末尾にある注文情報を参照してください。



## アプリケーション使用事例



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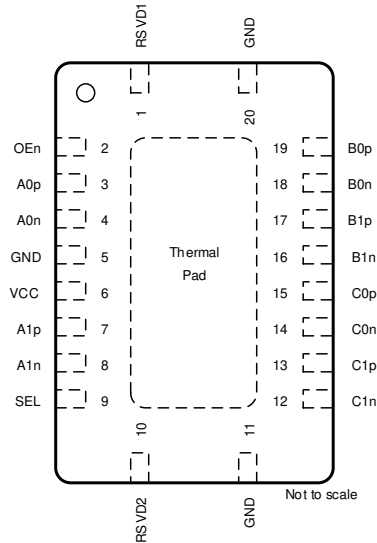
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## 4 Revision History

資料番号末尾の英字は改訂を表しています。その改訂履歴は英語版に準じています。

Changes from Revision * (May 2020) to Revision A (May 2022)	Page
• 文書全体にわたって表、図、相互参照の採番方法を更新.....	1
• 「特長」セクションの単一 V <sub>CC</sub> 電源電圧を更新.....	1
• Updated the <i>RSVD1</i> and <i>RSVD2</i> description.....	3
• Changed single supply voltage V <sub>CC</sub> from: 3.3 V to: 3.3 or 1.8 V.....	3

## 5 Pin Configuration and Functions



**5-1. RKS Package, 20-Pin VQFN (Top View)**

**表 5-1. Pin Functions**

PIN		TYPE <sup>(1)</sup>	DESCRIPTION
NAME	NO.		
A0n	4	I/O	Port A, channel 0, high-speed negative signal
A0p	3	I/O	Port A, channel 0, high-speed positive signal
A1n	8	I/O	Port A, channel 1, high-speed negative signal
A1p	7	I/O	Port A, channel 1, high-speed positive signal
B0n	18	I/O	Port B, channel 0, high-speed negative signal (connector side)
B0p	19	I/O	Port B, channel 0, high-speed positive signal (connector side)
B1n	16	I/O	Port B, channel 1, high-speed negative signal
B1p	17	I/O	Port B, channel 1, high-speed positive signal
C0n	14	I/O	Port C, channel 0, high-speed negative signal
C0p	15	I/O	Port C, channel 0, high-speed positive signal
C1n	12	I/O	Port C, channel 1, high-speed negative signal
C1p	13	I/O	Port C, channel 1, high-speed positive signal
GND	5, 11, 20	G	Ground
OEn	2	I	Active-low chip enable. The pin can be connected to GND if always on functional behavior is desired. L: Normal operation, H: Shutdown. If always ON, behavior of the device is desired. The pin can be permanently connected to GND.
RSVD1	1	NA	Reserved pins. Connect both pins to V <sub>CC</sub>
RSVD2	10	NA	
SEL	9	I	Port select pin. L: Port A to Port B, H: Port A to Port C
V <sub>CC</sub>	6	P	3.3 V or 1.8 V power

(1) I = input, O = output, G = ground, P = power

## 6 Specifications

### 6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

		MIN	MAX	UNIT	
V <sub>CC-ABS</sub> MAX	Supply voltage	-0.5	4	V	
V <sub>HS-ABS</sub> MAX	Voltage	Differential I/O	-0.5	2.4	V
V <sub>CTR-ABS</sub> MAX	Voltage	Control pins	-0.5	V <sub>CC</sub> +0.4	V
T <sub>STG</sub>	Storage temperature	-65	150	°C	

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

### 6.2 ESD Ratings

		VALUE	UNIT
V <sub>ESD</sub>	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 <sup>(1)</sup>	±2000
		Charged-device model (CDM), per JEDEC specification JESD22-C101 <sup>(2)</sup>	±1000

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.  
 (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

### 6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	TYP	MAX	UNIT	
V <sub>CC</sub>	Supply Voltage	1.8 V mode	1.71	1.8	1.98	V
		3.3 V mode	3.0	3.3	3.6	V
V <sub>CC-RAMP</sub>	Supply voltage ramp time	0.1		100	ms	
V <sub>IH</sub>	Input high voltage	SEL, OE pins	0.75 V <sub>CC</sub>		V	
V <sub>IL</sub>	Input low voltage	SEL, OE pins		0.25 V <sub>CC</sub>	V	
V <sub>DIFF</sub>	High-speed signal pins differential voltage	0		1.8	V <sub>pp</sub>	
V <sub>CM</sub>	High speed signal pins common mode voltage	VCC 1.8 V mode	0	1.2	V	
		VCC 3.3 V mode	0	1.8	V	
T <sub>A</sub>	Operating free-air/ambient temperature	TMUXHS4212	0	70	°C	
		TMUXHS4212I	-40	105	°C	

### 6.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>		TMUXHS4212	UNIT
		RKS (VQFN)	
		20 PINS	
R <sub>θJA</sub>	Junction-to-ambient thermal resistance - High K	53.0	°C/W
R <sub>θJC(top)</sub>	Junction-to-case (top) thermal resistance	52.3	°C/W
R <sub>θJB</sub>	Junction-to-board thermal resistance	27.1	°C/W
ψ <sub>JT</sub>	Junction-to-top characterization parameter	2.9	°C/W
ψ <sub>JB</sub>	Junction-to-board characterization parameter	26.9	°C/W
R <sub>θJC(bot)</sub>	Junction-to-case (bottom) thermal resistance	11.1	°C/W

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

## 6.5 Electrical Characteristics

over operating free-air temperature and supply voltage range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$I_{CC}$	Device active current	$OEn = 0$ ; $0 V \leq V_{CM} \leq 1.8$ ; $SEL = 0$ or $V_{CC}$		180	250	$\mu A$
$I_{STDN}$	Device shutdown current	$OEn = V_{CC}$		2	5	$\mu A$
$C_{ON}$	Output ON capacitance to GND	$OEn = 0$			0.6	pF
$R_{ON}$	Output ON resistance	$0 V \leq V_{CM} \leq 1.8 V$ ; $I_O = -8 mA$		5	8.4	$\Omega$
$\Delta R_{ON}$	On-resistance match between pairs for the same channel at same $V_{CM}$ , $V_{CC}$ and $T_A$				0.5	$\Omega$
$R_{FLAT\_ON}$	On-resistance flatness $R_{ON}(MAX) - R_{ON}(MIN)$ over $V_{CM}$ range for the same channel at same $V_{CC}$ and $T_A$				0.75	$\Omega$
$I_{IH,CTRL}$	Input high current, control pins (SEL, OEn)	$V_{IN} = V_{CC}$			2	$\mu A$
$I_{IL,CTRL}$	Input low current, control pins (SEL, OEn)	$V_{IN} = 0 V$			1	$\mu A$
$R_{CM,HS}$	Common mode resistance to ground on Ax pins	Each pin to GND		1.0	1.6	M $\Omega$
$I_{IH,HS,SEL}$	Input high current, high-speed pins [Ax/Bx/Cx][p/n]	$V_{IN} = 1.8 V$ for selected port - A and B with $SEL = 0$ , and A and C with $SEL = V_{CC}$			8	$\mu A$
$I_{IH,HS,NSEL}$	Input high current, high-speed pins [Ax/Bx/Cx][p/n]	$V_{IN} = 1.8 V$ for non-selected port - C with $SEL = 0$ , and B with $SEL = V_{CC}$ (1)			150	$\mu A$
$I_{IL,HS}$	Input low current, high-speed pins [Ax/Bx/Cx][p/n]	$V_{IN} = 0 V$			1	$\mu A$
$I_{HIZ,HS}$	Leakage current through turned off switch between Ax[p/n] to [B]x[p/n] and [C]x[p/n]	$OEn = V_{CC}$ ; Ax[p/n] = 1.8 V, [B and C]x[p/n] = 0 V and Ax[p/n] = 0 V, [B and C]x[p/n] = 1.8 V			5	$\mu A$
$R_{A,p2n}$	DC Impedance between p and n for Ax pins	$OEn = 0$ and $V_{CC}$		20		K $\Omega$

(1) There is a 20-k $\Omega$  pull-down in non-selected port.

## 6.6 High-Speed Performance Parameters

PARAMETER	TEST CONDITION	MIN	TYP	MAX	UNIT
$I_L$	Differential insertion loss	$f = 10 MHz$		-0.5	dB
		$f = 2.5 GHz$		-0.8	
		$f = 4 GHz$		-1.1	
		$f = 5 GHz$		-1.3	
		$f = 8 GHz$		-1.8	
		$f = 10 GHz$		-2.1	
BW	-3-dB bandwidth		13		GHz
$R_L$	Differential return loss	$f = 10 MHz$		-28	dB
		$f = 2.5 GHz$		-17	
		$f = 4 GHz$		-13	
		$f = 5 GHz$		-13	
		$f = 8 GHz$		-12	
		$f = 10 GHz$		-12	
$O_{IRR}$	Differential OFF isolation	$f = 10 MHz$		-55	dB
		$f = 2.5 GHz$		-27	
		$f = 4 GHz$		-24	
		$f = 5 GHz$		-22	
		$f = 8 GHz$		-20	
		$f = 10 GHz$		-18	
$X_{TALK}$	Differential crosstalk	$f = 10 MHz$		-65	dB
		$f = 2.5 GHz$		-40	
		$f = 4 GHz$		-35	
		$f = 5 GHz$		-32	
		$f = 8 GHz$		-30	
		$f = 10 GHz$		-27	

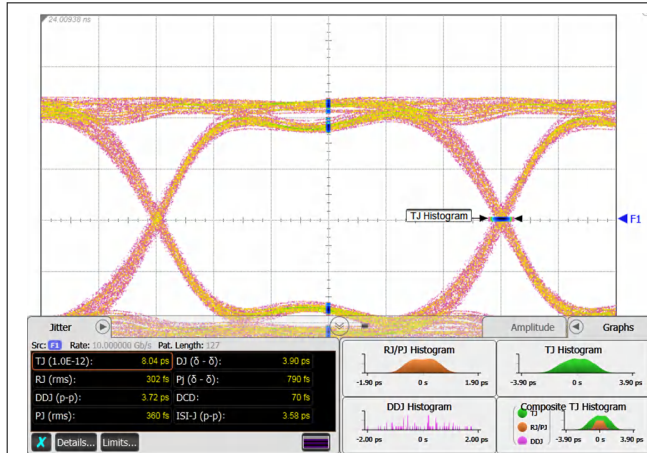
## 6.6 High-Speed Performance Parameters (continued)

PARAMETER		TEST CONDITION	MIN	TYP	MAX	UNIT
SCD11,22	Mode conversion - differential to common mode	$f = 5 \text{ GHz}$		-29		dB
SCD21,12	Mode conversion - differential to common mode	$f = 5 \text{ GHz}$		-27		dB
SDC11,22	Mode conversion - common mode to differential	$f = 5 \text{ GHz}$		-29		dB
SDC21,12	Mode conversion - common mode to differential	$f = 5 \text{ GHz}$		-26		dB

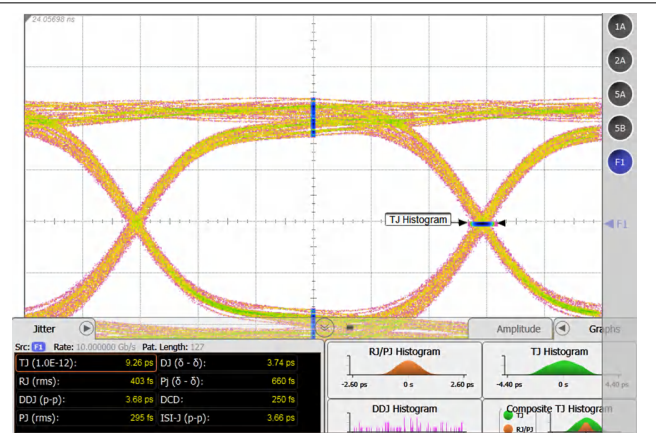
## 6.7 Switching Characteristics

PARAMETER			MIN	TYP	MAX	UNIT
$t_{PD}$	Switch propagation delay	$f = 1 \text{ GHz}$			70	ps
$t_{SW\_ON\_CM\_SHIFT}$	Switching time SEL-to-Switch ON	For different CMV			5	us
$t_{SW\_ON}$	Switching time SEL-to-Switch ON	For same CMV			100	ns
$t_{SW\_OFF\_CM\_SHIFT}$	Switching time SEL-to-Switch OFF	For different CMV			1	us
$t_{SW\_OFF}$	Switching time SEL-to-Switch OFF	For same CMV			100	ns
$t_{SK\_INTRA}$	Intra-pair output skew between P and N pins for same channel	$f = 1 \text{ GHz}$			8	ps
$t_{SK\_INTER}$	Inter-pair output skew between channels	$f = 1 \text{ GHz}$			10	ps

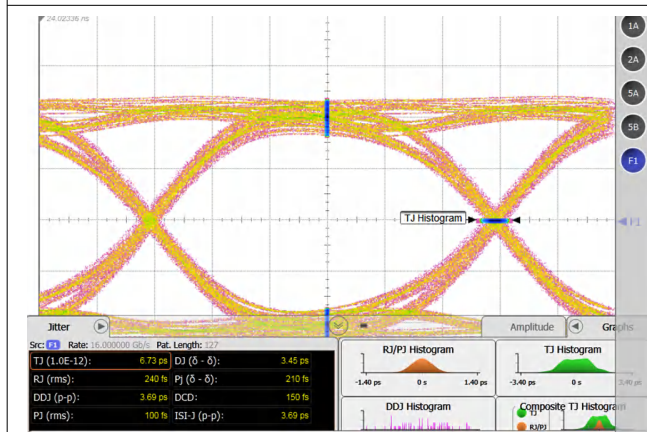
## 6.8 Typical Characteristics



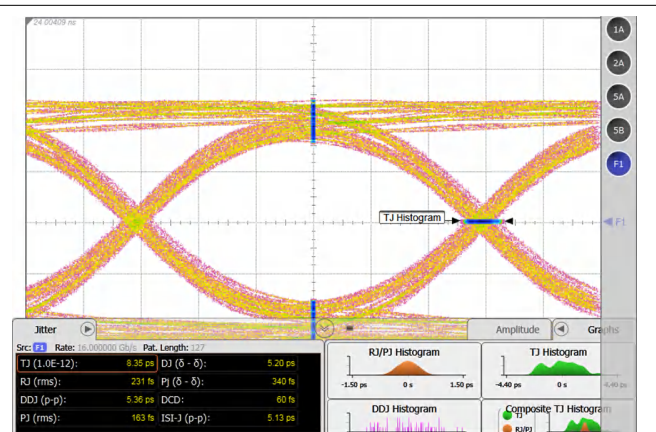
**6-1. Jitter Decomposition of 10 Gbps PRBS-7 Signals Through Calibration Traces in TI Evaluation Board**



**6-2. Jitter Decomposition of 10 Gbps PRBS-7 Signals Through a Typical TMUXHS4212 Channel in TI Evaluation Board**

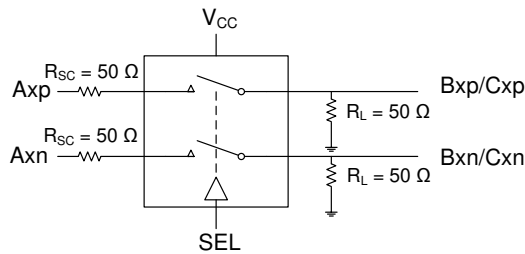


**6-3. Jitter Decomposition of 16 Gbps PRBS-7 Signals Through Calibration Traces in TI Evaluation Board**

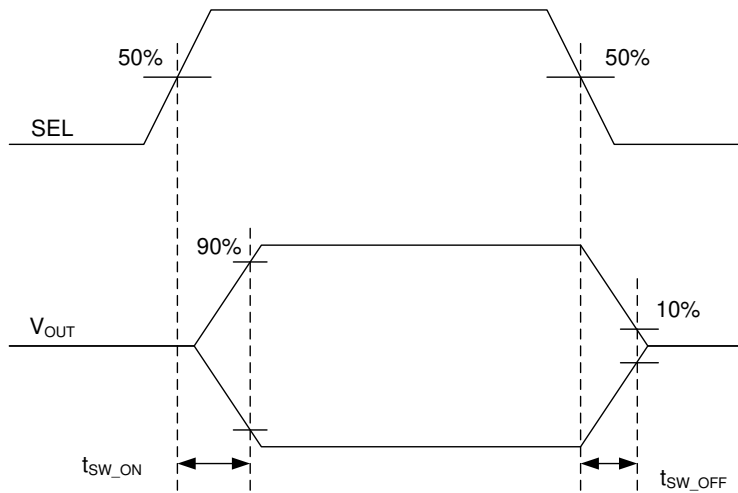


**6-4. Jitter Decomposition of 16 Gbps PRBS-7 Signals Through a Typical TMUXHS4212 Channel in TI Evaluation Board**

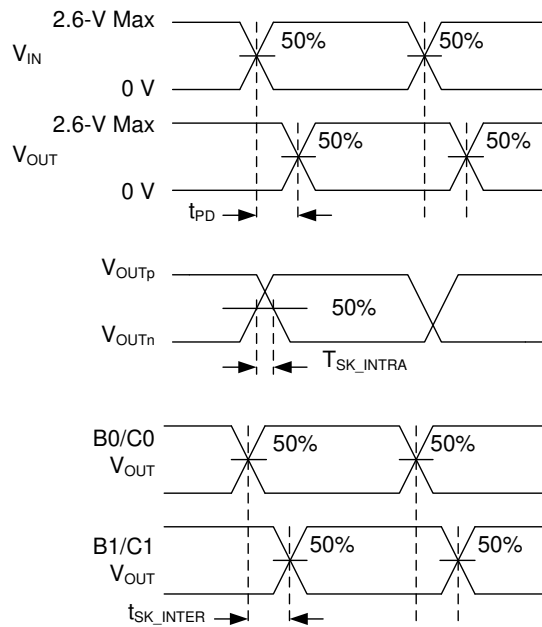
## 7 Parameter Measurement Information



**7-1. Test Setup**



**7-2. Switch On and Off Timing Diagram**



**7-3. Timing Diagrams and Test Setup**



## 8 Detailed Description

### 8.1 Overview

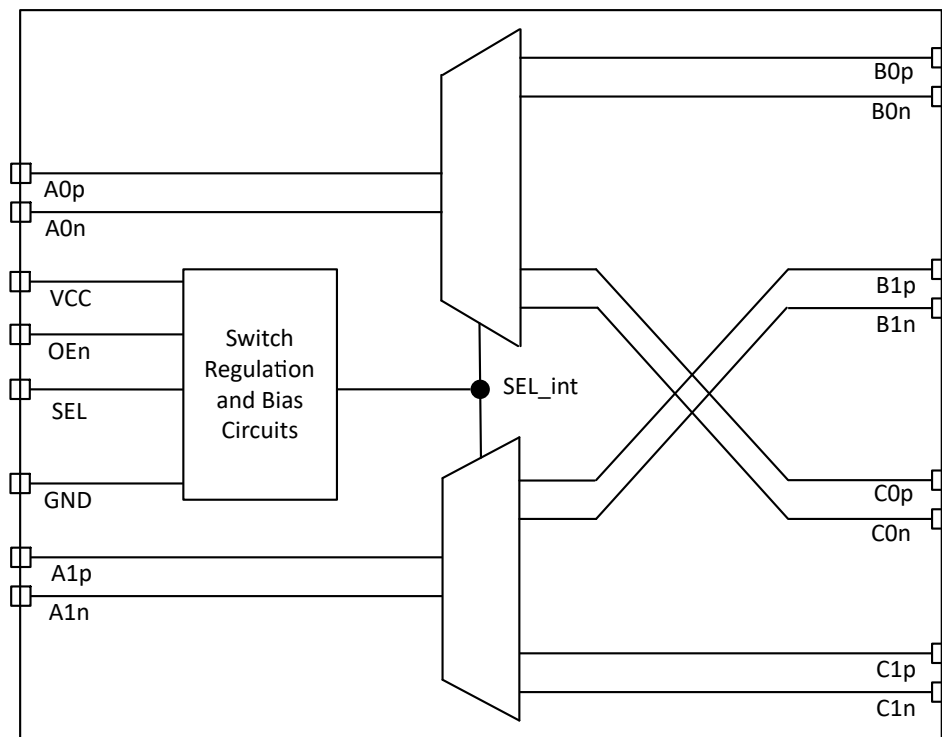
The TMUXHS4212 is a generic analog differential passive mux or demux that can work for any high-speed interface with differential signaling where common mode voltage (CMV) and differential amplitude up to 1800 mVpp. It employs adaptive input voltage tracking that ensures the channel remains unchanged for the entire common mode voltage range. Two channels of the device can be used for electrical signals that have different CMV between them. Two channels can also be used in such a way that the device switches two different interface signals with different data and electrical characteristics.

Excellent dynamic characteristics of the device allow high speed switching with minimum attenuation to the signal eye diagram with very little added jitter. While the device is recommended for the interfaces up to 16 Gbps, actual data rate where the device can be used highly depends on the electrical channels. For low loss channels where adequate margin is maintained, the device can potentially be used for higher data rates.

The TMUXHS4212 is only recommended for differential signaling. However, certain low voltage single ended signaling (such as, Mipi DPHY LP signaling) can pass through the device. It is recommended to analyze the data line biasing of the device for such single ended use cases.

The TMUXHS4212 comes in two different pinout options that provide layout implementation choices.

### 8.2 Functional Block Diagram



### 8.3 Feature Description

#### 8.3.1 Output Enable and Power Savings

The TMUXHS4212 has two power modes, active/normal operating mode and standby/shutdown mode. During standby mode, the device consumes very-little current to achieve ultra low power in systems where power saving is critical. To enter standby mode, the OEn control pin is pulled high through a resistor and must remain high. For active/normal operation, the OEn control pin should be pulled low to GND or dynamically controlled to switch between H or L.

The TMUXHS4212 consumes 180  $\mu$ A of power when operational and has a shutdown mode exercisable by the OEn pin resulting < 2  $\mu$ A.

### 8.3.2 Data Line Biasing

The TMUXHS4212 has a weak pull-down of 1 M $\Omega$  from A[0/1][p/n] pins to GND. While these resistors biases the device data channels to common mode voltage (CMV) of 0 V with very weak strength, it is recommended that the device is biased by a stronger impedance from either side of the device to a valid value in the range of 0 – 1.8 V. To avoid double biasing, ensure that the appropriate ac coupling capacitors are on either side of the device.

In certain use cases, if both sides of the TMUXHS4212 are ac coupled, then it is recommended to use appropriate CMV biasing for the device. 10 k $\Omega$  to GND or any other bias voltage in the CMV range for each A[0/1][p/n] pin will suffice for most use cases.

The high-speed data ports incorporate 20 k $\Omega$  pull-down resistors that are switched in when a port is not selected and switched out when the port is selected. For example, when SEL = L, the C[0/1][p/n] pins have 20 k $\Omega$  resistors to GND. The feature ensures that the unselected port is always biased to a known voltage for long term reliability of the device and the electrical channel.

The positive and negative terminals of data pins A[0/1] have a weak (20 k $\Omega$ ) differential resistor for device switch regulation operation. This does not impact signal integrity or functionality of high speed differential signaling that typically has much stronger differential impedance (such as 100  $\Omega$ ).

### 8.4 Device Functional Modes

**表 8-1. Port Select Control Logic<sup>(1)</sup>**

PORT A CHANNEL	PORT B OR PORT C CHANNEL CONNECTED TO PORT A CHANNEL	
	SEL = L	SEL = H
A0p	B0p	C0p
A0n	B0n	C0n
A1p	B1p	C1p
A1n	B1n	C1n

- (1) The TMUXHS4212 can tolerate polarity inversions for all differential signals on Ports A, B, and C. Ensure that the same polarity is maintained on Port A versus Ports B or C in such flexible implementation.

## 9 Application and Implementation

### Note

以下のアプリケーション情報は、TI の製品仕様に含まれるものではなく、TI ではその正確性または完全性を保証いたしません。個々の目的に対する製品の適合性については、お客様の責任で判断していただくこととなります。お客様は自身の設計実装を検証しテストすることで、システムの機能を確認する必要があります。

### 9.1 Application Information

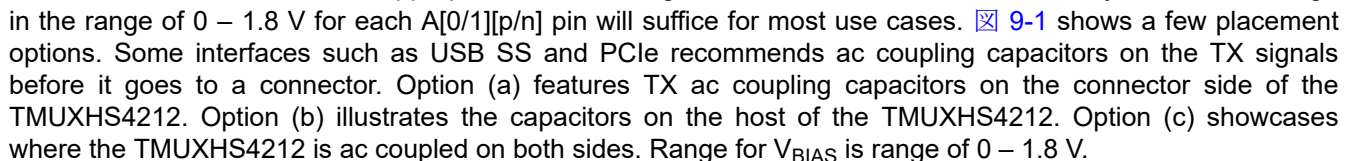
The TMUXHS4212 is a generic 2-channel high-speed mux or demux type of switch that can be used for routing high-speed signals between two different locations on a circuit board. The TMUXHS4212 supports many high-speed data protocols, provided the signals' differential amplitude and common mode voltage are within <1800 mVpp and a common mode voltage is <1.8 V. The TMUXHS4212 can be used for many high speed interfaces including the following:

- Universal Serial Bus (USB) 3.2 Gen 1.0 and 2.0
- USB Type-C
- Peripheral Component Interconnect Express (PCIe™) Gen 1.0, 2.0, 3.0, and 4.0
- Serial ATA (SATA/eSATA)
- Serial Attached SCSI (SAS)
- DisplayPort (DP) 1.4 and 2.0
- Thunderbolt™ (TBT) 3.0
- Mipi Camera Serial Interface (CSI-2), Display Serial Interface (DSI)
- Low Voltage Differential Signalling (LVDS)
- Serdes Framer Interface (SFI)
- Ethernet Interfaces

The device's mux or demux selection pin SEL can easily be controlled by an available GPIO pin of a controller or hard tie to voltage level H or L as an application requires.

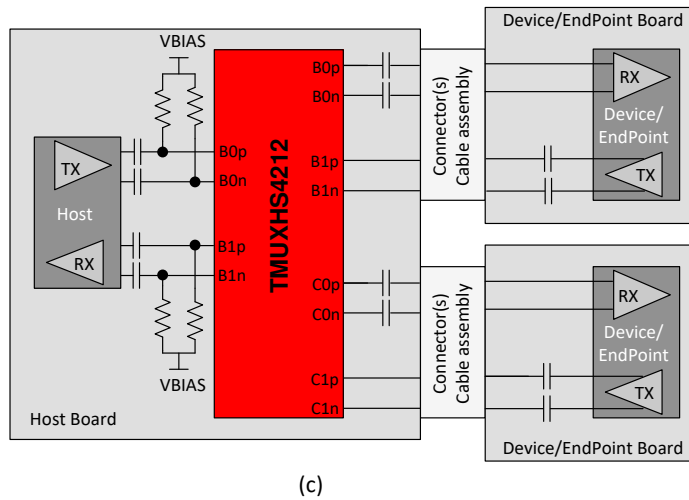
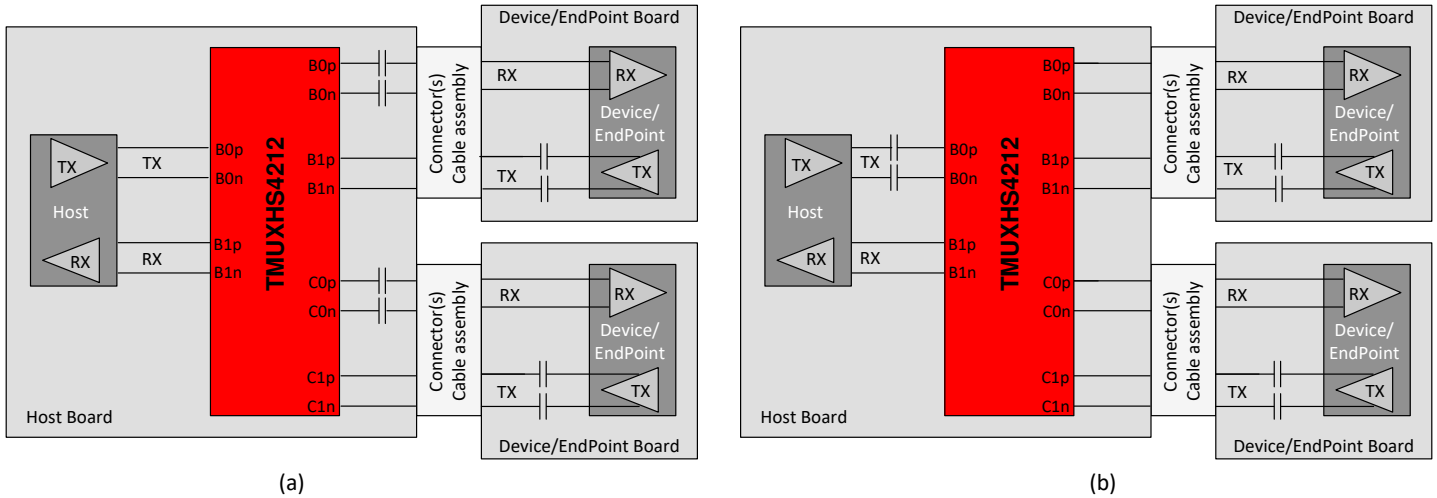
The TMUXHS4212 with adaptive voltage tracking technology can support applications where the common mode is different between the RX and TX pair. The switch paths of the TMUXHS4212 have internal weak pull-down resistors of 1 MΩ on the A port pins. While these resistors bias the device data channels to common mode voltage (CMV) of 0 V with a weak strength, it is recommended that the device is biased from either side of the device to a valid value in the range of 0 – 1.8 V. It is expected that the system/host controller and Device/End point common mode bias impedances are much stronger (smaller) than the TMUXHS4212 internal pull-down resistors; therefore, they are not impacted.

Many interfaces require ac coupling between the transmitter and receiver. The 0201 or 0402 capacitors are the preferred option to provide ac coupling. Avoid the 0603 and 0805 size capacitors and C-packs. When placing ac coupling capacitors, symmetric placement is best. The capacitor value must be chosen according to the specific interface the device is being used. The value of the capacitor should match for the positive and negative signal pair. For many interfaces (such as, USB 3.2 and PCIe) the designer should place them along the TX pairs on the system board, which are usually routed on the top layer of the board. Depending upon the application and interface specifications, use the appropriate value for ac coupling capacitors.

The ac coupling capacitors have several placement options. Typical use cases warrant that the capacitors are placed on one side of the TMUXHS4212. In certain use cases, if both sides of the TMUXHS4212 are ac coupled, then it is recommended to use appropriate CMV biasing for the device. 10 kΩ to GND or any other bias voltage in the range of 0 – 1.8 V for each A[0/1][p/n] pin will suffice for most use cases.  9-1 shows a few placement options. Some interfaces such as USB SS and PCIe recommends ac coupling capacitors on the TX signals before it goes to a connector. Option (a) features TX ac coupling capacitors on the connector side of the TMUXHS4212. Option (b) illustrates the capacitors on the host of the TMUXHS4212. Option (c) showcases where the TMUXHS4212 is ac coupled on both sides. Range for V<sub>BIAS</sub> is range of 0 – 1.8 V.

**TMUXHS4212**

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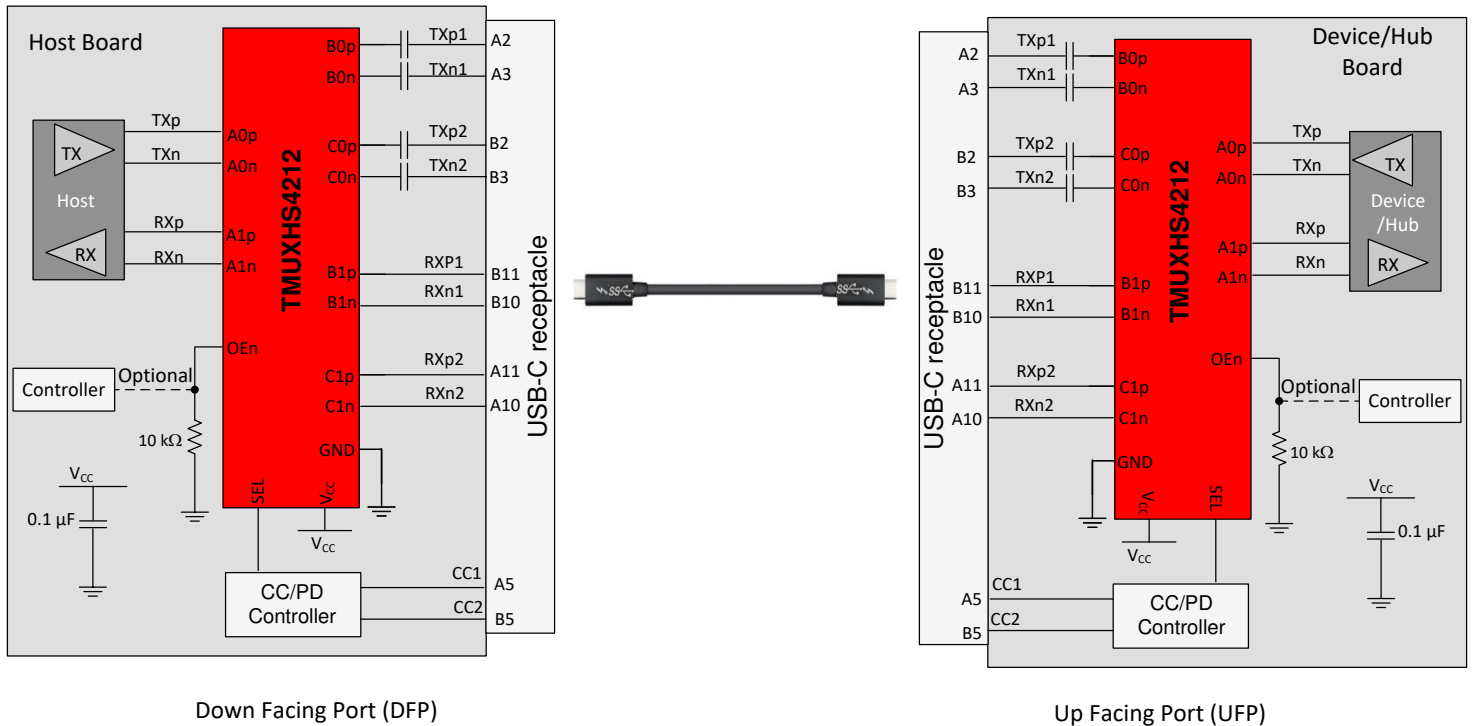


**9-1. AC Coupling Capacitors Placement Options Between Host and Device/Endpoint Through TMUXHS4212**

## 9.2 Typical Applications

### 9.2.1 USB 3.2 Implementation for USB Type-C

The TMUXHS4212 can be used in USB Type-C implementation to mux USB 3.2 superspeed signals (TX1 and RX1 pairs versus TX2 and RX2 pairs) to accommodate plug flips. In typical use cases, the mux selection is done by a USB Type-C Channel Configuration (CC) or Power Delivery (PD) controller. The device can be used on a USB Type-C DFP, UFP, or DRP port. [Figure 9-2](#) shows two USB Type-C connector applications with both a host and device side. The cable between the two connectors swivels the pairs to properly route the signals to the correct pin. The other applications are more generic because different connectors can be used.



**Figure 9-2. USB 3.2 Implementation for USB Type-C Connector**

#### 9.2.1.1 Design Requirements

The TMUXHS4212 can be designed into many different applications. All the applications have certain requirements for the system to work properly. The TMUXHS4212 requires  $3.3\text{ V} \pm 10\%$   $V_{CC}$  rail. The OEn pin must be low for the device to work; otherwise, it disables the outputs. A processor can drive the OEn pin. The expectation is that one side of the device has ac coupling capacitors. [Table 9-1](#) provides information on expected values to perform properly.

**Table 9-1. Design Parameters**

DESIGN PARAMETER	VALUE
$V_{CC}$	3.3 V
AXp/n, BXp/n, CXp/n CM input voltage	0 V to 1.8 V
Control/OEn pin max voltage for low	0.5 V
Control/OEn pin min voltage for high	1.42 V
ac coupling capacitor	75 nF to 265 nF
$R_{BIAS}$ ( <a href="#">Figure 9-2</a> ) when needed	1 kΩ to 100 kΩ

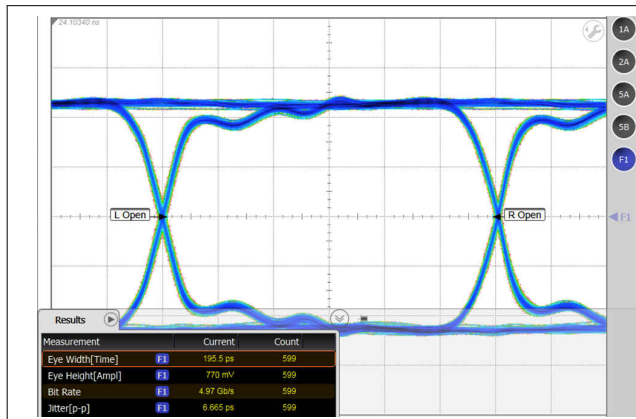
### 9.2.1.2 Detailed Design Procedure

The TMUXHS4212 is a high-speed passive switch device that can behave as a mux or demux. Because this is a passive switch, signal integrity is important because the device provides no signal conditioning capability. The device can support 2 to 3 inches of board trace and a connector on either end.

To design in the TMUXHS4212, the designer needs to understand the following:

- Determine the loss profile between circuits that are to be muxed or demuxed.
- Provide clean impedance and electrical length matched board traces.
- Provide a control signal for the SEL and OEn pins.
- The thermal pad must be connected to ground.
- See the application schematics on recommended decouple capacitors from  $V_{CC}$  pins to ground.

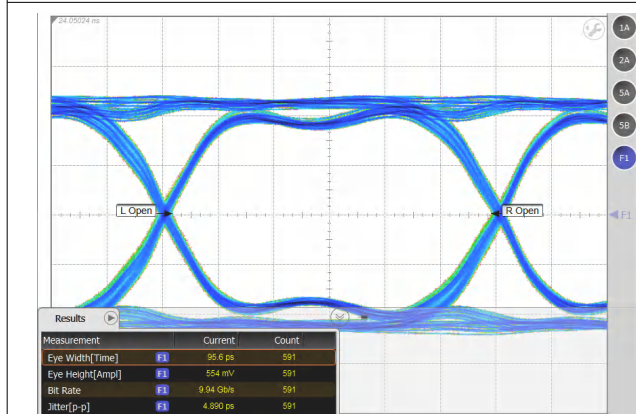
### 9.2.1.3 Application Curves



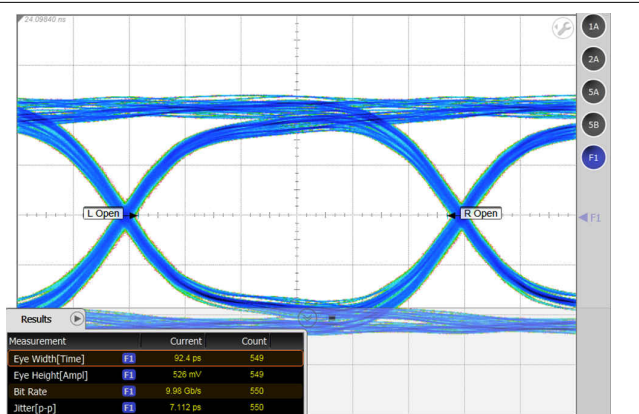
9-3. 5 Gbps PRBS-7 Signals Through Calibration Traces in TI Evaluation Board



9-4. 5 Gbps PRBS-7 Signals Through a Typical TMUXHS4212 Channel in TI Evaluation Board



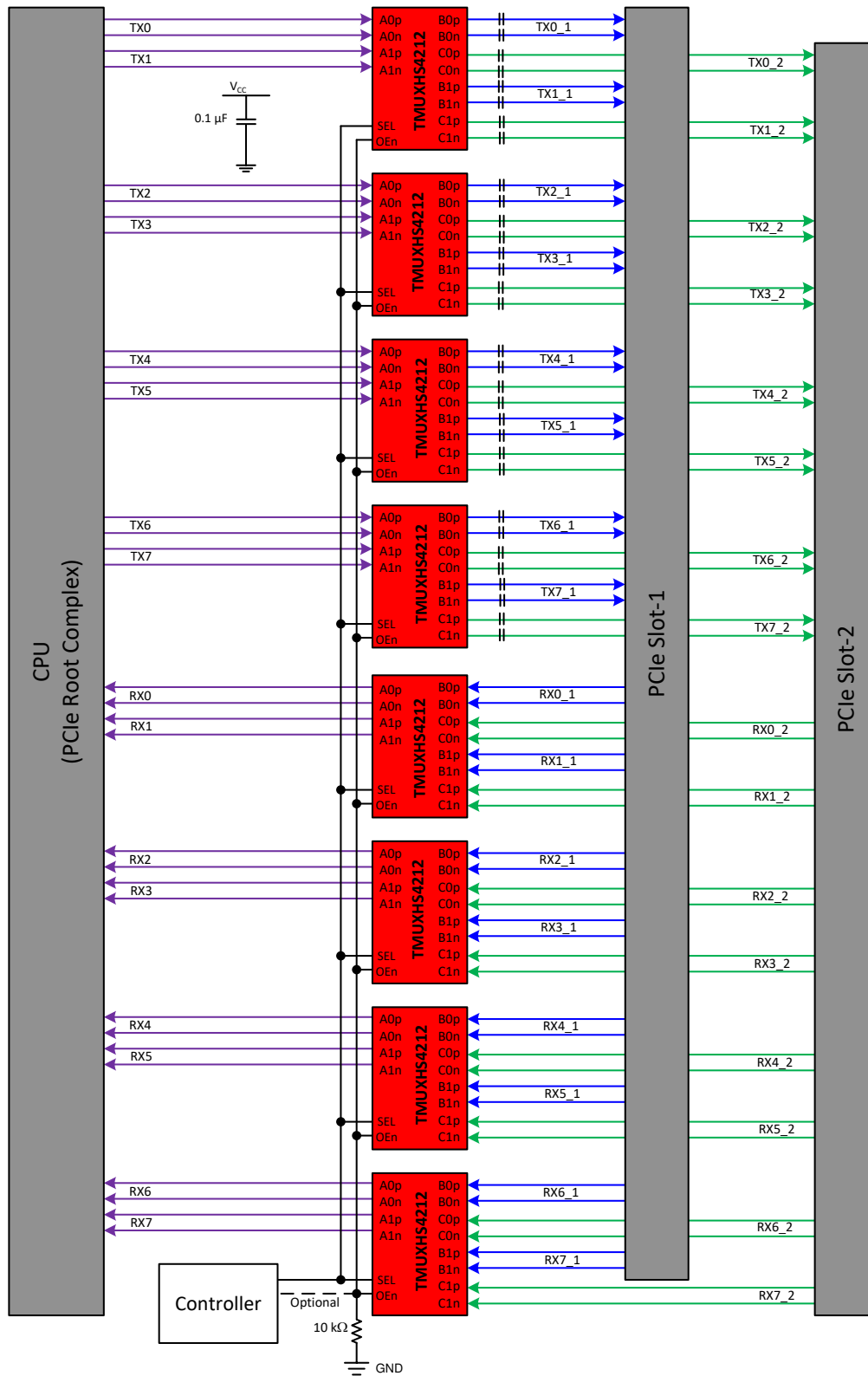
9-5. 10 Gbps PRBS-7 Signals Through Calibration Traces in TI Evaluation Board



9-6. 10 Gbps PRBS-7 Signals Through a Typical TMUXHS4212 Channel in TI Evaluation Board

### 9.2.2 PCIe Lane Muxing

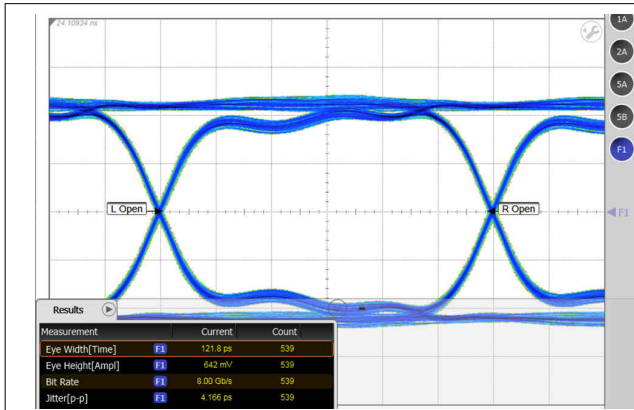
The TMUXHS4212 can be used to switch PCIe lanes between two slots. In many PC and server motherboards, the CPU does not have enough PCIe lanes to provide desired system flexibility for end customers. In such applications, the TMUXHS4212 can be used to switch PCIe TX and RX lanes between two slots. [Figure 9-7](#) provides a schematic where eight TMUXHS4212 devices are used to switch eight PCIe TX and eight RX lanes. Note: the common mode voltage (CMV) bias for the TMUXHS4212 must be within the range of 0 – 1.8 V. In implementations where receiver CMV bias of a PCIe root complex or an end point can not be ensured within the CMV range, additional DC blocking capacitors and appropriate CMV biasing must be implemented.



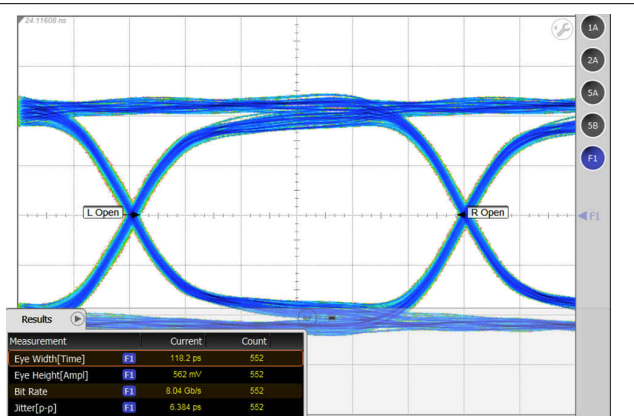
**9-7. PCIe Lane Muxing**



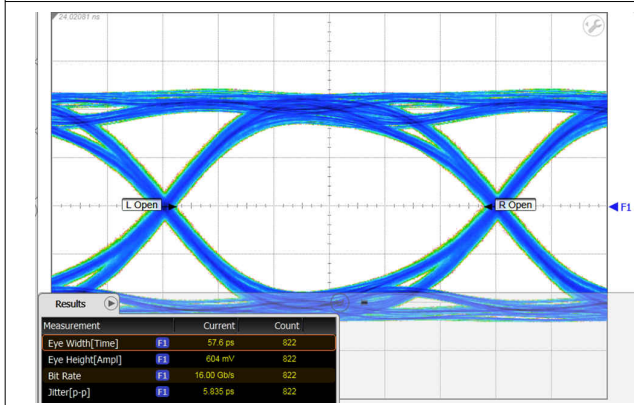
### 9.2.2.1 Application Curves



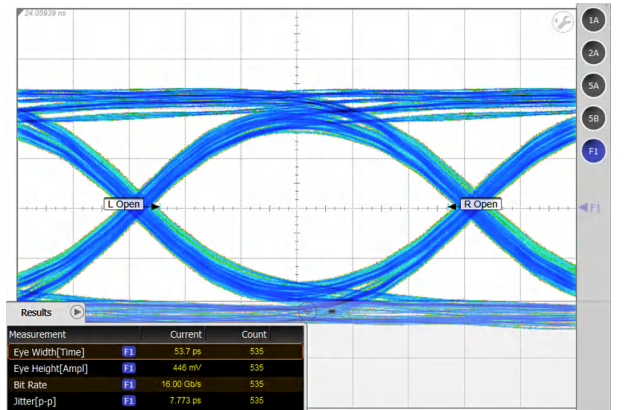
**9-8. 8 Gbps PRBS-7 Signals Through Calibration Traces in TI Evaluation Board**



**9-9. 8 Gbps PRBS-7 Signals Through a Typical TMUXHS4212 Channel in TI Evaluation Board**



**9-10. 16 Gbps PRBS-7 Signals Through Calibration Traces in TI Evaluation Board**



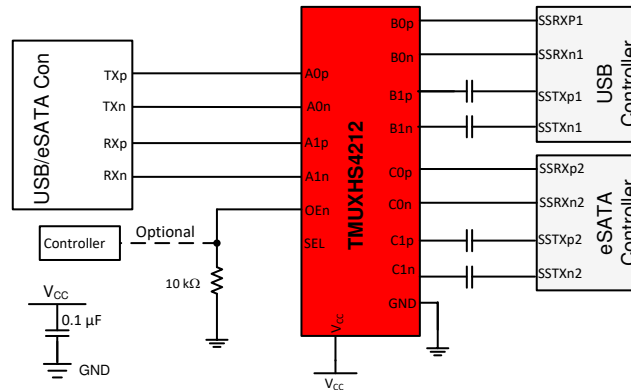
**9-11. 16 Gbps PRBS-7 Signals Through a Typical TMUXHS4212 Channel in TI Evaluation Board**

**TMUXHS4212**

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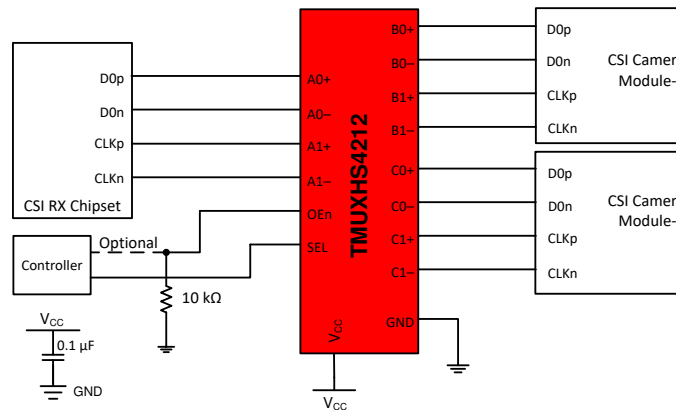
**9.3 Systems Examples**

**9.3.1 USB/eSATA**



**9-12. eSATA and USB 3.2 Combo Connector**

**9.3.2 MIPI Camera Serial Interface**



**9-13. CSI Camera Selection**

**10 Power Supply Recommendations**

The TMUXHS4212 does not require a power supply sequence. TI, however, recommends that OEn is asserted low after the device supply V<sub>CC</sub> is stable and in specification. TI also recommends to place ample decoupling capacitors at the device V<sub>CC</sub> near the pin.

## 11 Layout

### 11.1 Layout Guidelines

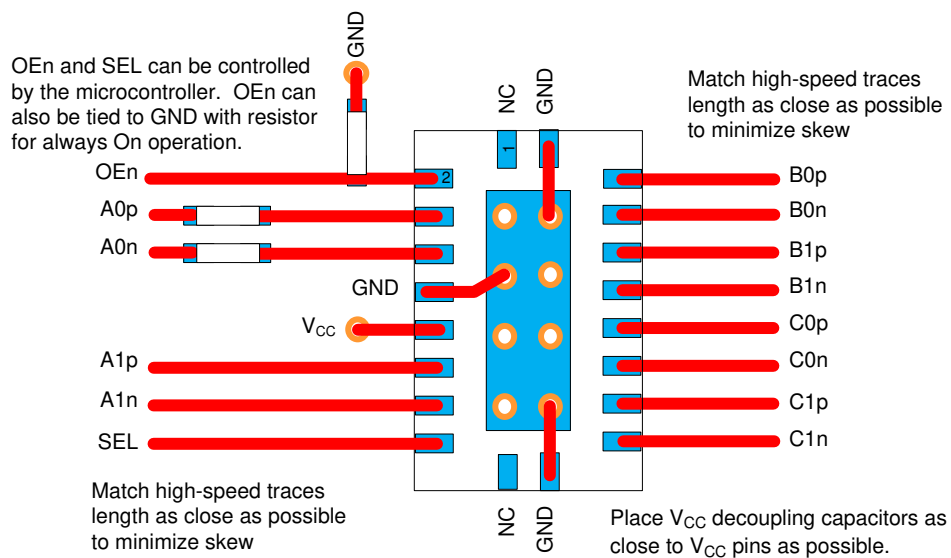
On a high-K board, TI always recommends to solder the Power-pad™ onto the thermal land. A thermal land is the area of solder-tinned-copper underneath the Power-pad package. On a high-K board, the TMUXHS4212 can operate over the full temperature range by soldering the Power-pad onto the thermal land without vias.

For high speed layout guidelines, refer to [High-Speed Layout Guidelines for Signal Conditioners and USB Hubs](#).

The designer must use a 1-oz Cu trace connecting the GND pins to the thermal land for the device to operate across the temperature range on a low-K board. A general PCB design guide for Power-pad packages is provided in [Power-pad Thermally-Enhanced Package](#).

### 11.2 Layout Example

☒ 11-1 shows a basic layout example for the application shown in [セクション 9.2.1](#)



☒ 11-1. TMUXHS4212 Layout Example

## 12 Device and Documentation Support

### 12.1 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on [ti.com](https://www.ti.com). Click on *Subscribe to updates* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

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### 12.4 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

### 12.5 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

## 13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TMUXHS4212IRKSR	ACTIVE	VQFN	RKS	20	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 105	HS4212	<a href="#">Samples</a>
TMUXHS4212IRKST	ACTIVE	VQFN	RKS	20	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 105	HS4212	<a href="#">Samples</a>
TMUXHS4212RKSR	ACTIVE	VQFN	RKS	20	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	HS4212	<a href="#">Samples</a>
TMUXHS4212RKST	ACTIVE	VQFN	RKS	20	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	HS4212	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TMUXHS4212IRKSR	VQFN	RKS	20	3000	180.0	12.4	2.8	4.8	1.2	4.0	12.0	Q1
TMUXHS4212IRKST	VQFN	RKS	20	250	180.0	12.4	2.8	4.8	1.2	4.0	12.0	Q1
TMUXHS4212RKSR	VQFN	RKS	20	3000	180.0	12.4	2.8	4.8	1.2	4.0	12.0	Q1
TMUXHS4212RKST	VQFN	RKS	20	250	180.0	12.4	2.8	4.8	1.2	4.0	12.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TMUXHS4212IRKSR	VQFN	RKS	20	3000	210.0	185.0	35.0
TMUXHS4212IRKST	VQFN	RKS	20	250	210.0	185.0	35.0
TMUXHS4212RKSR	VQFN	RKS	20	3000	210.0	185.0	35.0
TMUXHS4212RKST	VQFN	RKS	20	250	210.0	185.0	35.0



## GENERIC PACKAGE VIEW

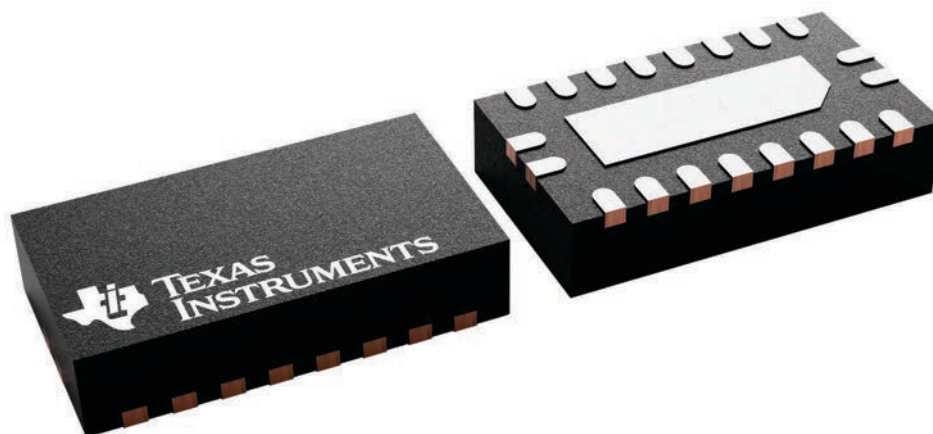
**RKS 20**

**VQFN - 1 mm max height**

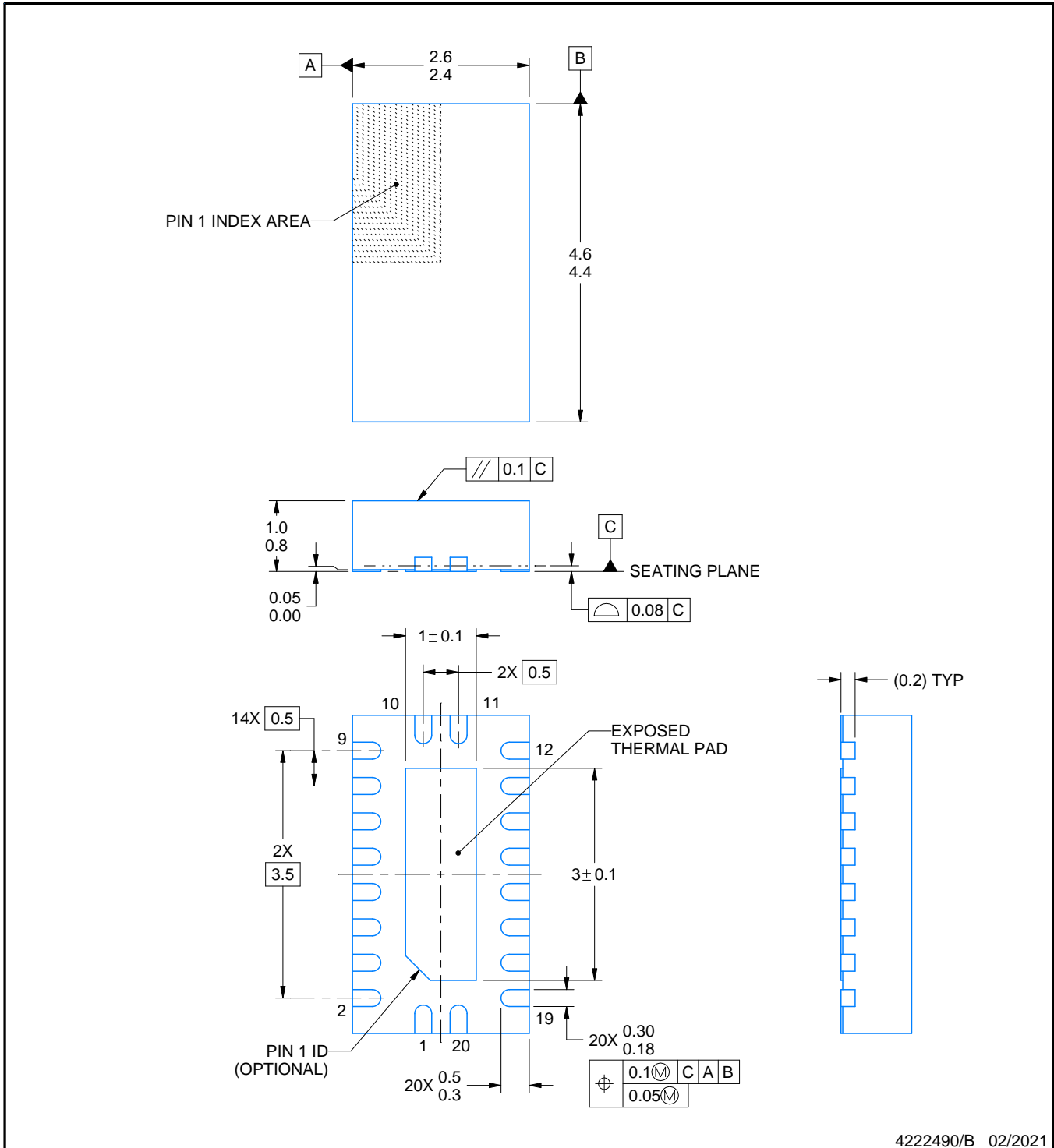
2.5 x 4.5, 0.5 mm pitch

PLASTIC QUAD FLATPACK - NO LEAD

This image is a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.



4226872/A



NOTES:

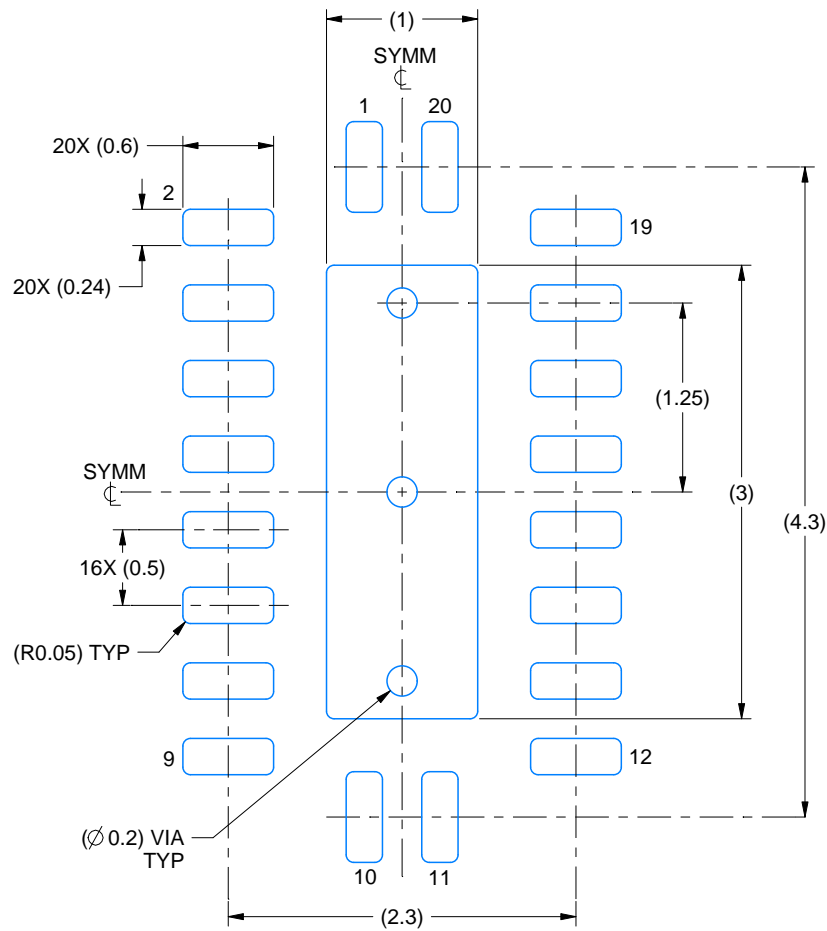
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

# EXAMPLE BOARD LAYOUT

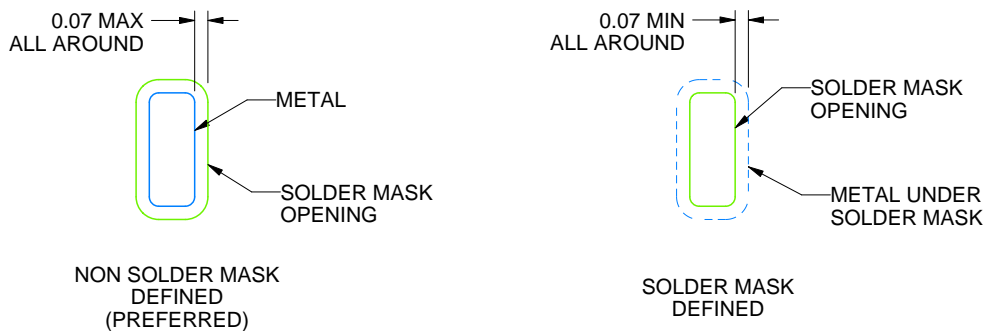
RKS0020A

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



LAND PATTERN EXAMPLE  
SCALE:20X



SOLDER MASK DETAILS

4222490/B 02/2021

NOTES: (continued)

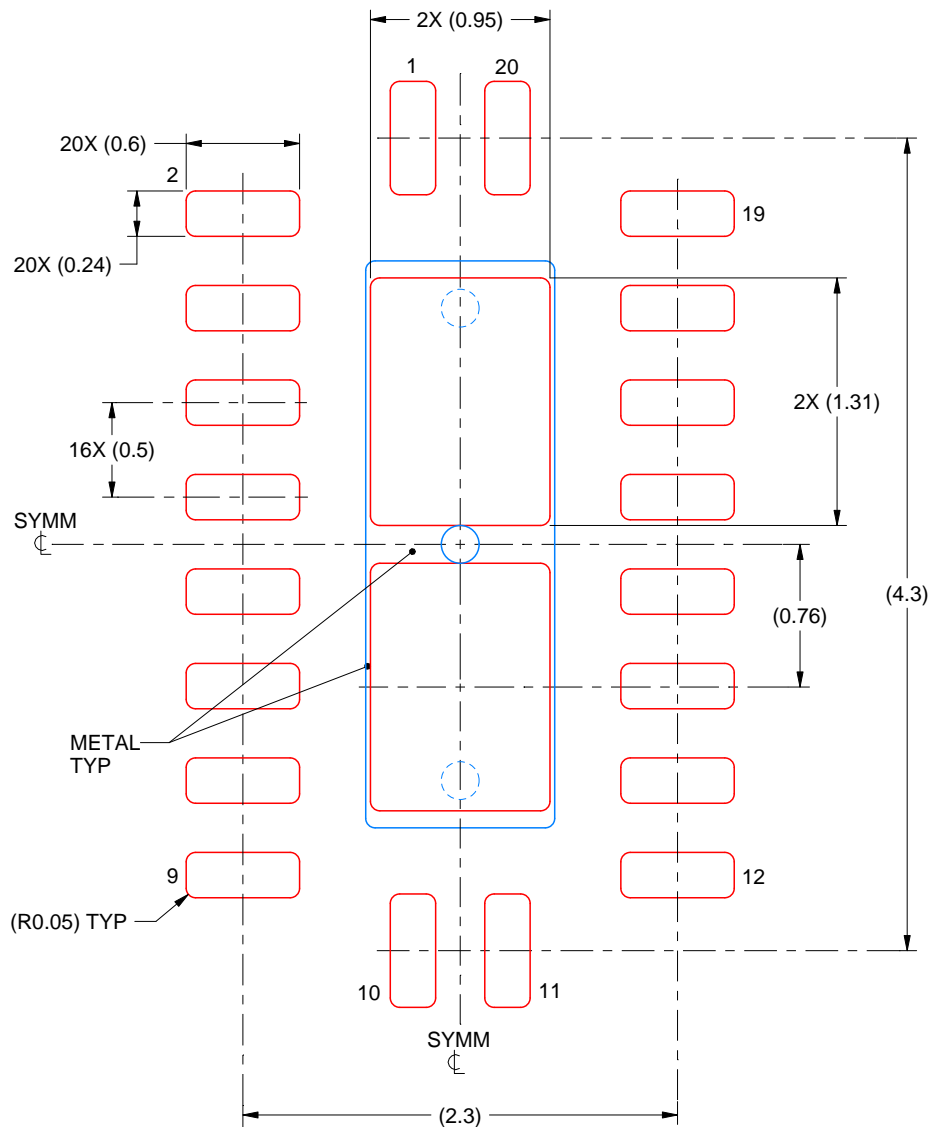
- This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/slua271](http://www.ti.com/lit/slua271)).
- Vias are optional depending on application, refer to device data sheet. If some or all are implemented, recommended via locations are shown.

# EXAMPLE STENCIL DESIGN

RKS0020A

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD  
83% PRINTED SOLDER COVERAGE BY AREA  
SCALE:25X

4222490/B 02/2021

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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